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(54) **METHOD OF FABRICATION OF AL/GE BONDING IN A WAFER PACKAGING ENVIRONMENT AND A PRODUCT PRODUCED THEREFROM**

VERFAHREN ZUR HERSTELLUNG VON AL/GE-BINDUNG IN EINER
WAFERVERKAPSELUNGSUMGEBUNG UND DARAUS HERGESTELLTES PRODUKT

PROCEDE DE FABRICATION D'UNE LIAISON AL/GE DANS UN ENVIRONNEMENT D'EMBALLAGE
DE TRANCHES ET PRODUIT FABRIQUE A PARTIR DE CE PROCEDE

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(73) Proprietor: **InvenSense, Inc.**
San Jose, CA 95110 (US)

(72) Inventors:
• **NASIRI, Steven, S.**
Saratoga, California 95070 (US)
• **FLANNERY, Anthony, Francis, Jr.**
Los Gatos, California 95030 (US)

(74) Representative: **Brookes Batchellor LLP**
1 Boyne Park
Tunbridge Wells Kent TN4 8EL (GB)

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EP 1 859 475 B8

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